



Description

JMT N And P-Channel Enhancement Mode MOSFET

Features

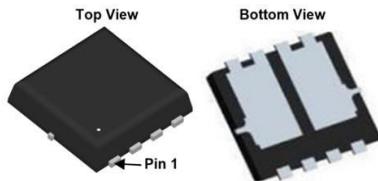
- N-Channel: 30V, 11A
 $R_{DS(ON)} < 16m\Omega$ @ $V_{GS} = 10V$
 $R_{DS(ON)} < 25m\Omega$ @ $V_{GS} = 4.5V$
- P-Channel: -30V, -11A
 $R_{DS(ON)} < 27m\Omega$ @ $V_{GS} = -10V$
 $R_{DS(ON)} < 43m\Omega$ @ $V_{GS} = -4.5V$
- Excellent Gate Charge x $R_{DS(ON)}$ Product(FOM)
- Very Low On-resistance $R_{DS(ON)}$
- Fast Switching Speed

Application

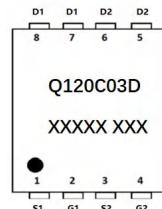
- Battery Protection
- Load Switch
- Power Management



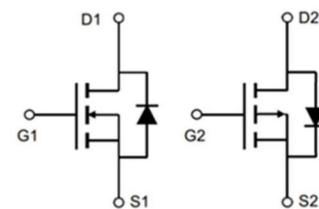
100% UIS TESTED!
100% ΔV_{ds} TESTED!



PDFN3x3-8L-D



Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
Q120C03D	JMTQ120C03D	TAPING	PDFN3x3-8L-D	13inch	5000	50000

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max. N-Channel	Max. P-Channel	Units
V_{DSS}	Drain-Source Voltage		30	-30	V
V_{GSS}	Gate-Source Voltage		± 20	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	11	-11	A
		$T_C = 100^\circ C$	7.2	-7.2	A
I_{DM}	Pulsed Drain Current ^{note1}		44	-44	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		20	25	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	3.3	5.6	W
R_{eJC}	Thermal Resistance, Junction to Case		38	22	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150		°C



JMTQ120C03D

N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}$, $V_{GS}=0\text{V}$	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1.0	1.4	2.5	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$, $I_D=10\text{A}$	-	12	16	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=5\text{A}$	-	18	25	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	584	-	pF
C_{oss}	Output Capacitance		-	112	-	pF
C_{rss}	Reverse Transfer Capacitance		-	96	-	pF
Q_g	Total Gate Charge	$V_{DS}=15\text{V}$, $I_D=10\text{A}$, $V_{GS}=10\text{V}$	-	15	-	nC
Q_{gs}	Gate-Source Charge		-	4.7	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	3.6	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=30\text{V}$, $I_D=10\text{A}$, $V_{GS}=10\text{V}$, $R_{REN}=3\Omega$	-	5	-	ns
t_r	Turn-on Rise Time		-	8	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	21	-	ns
t_f	Turn-off Fall Time		-	7	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	11	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	44	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=11\text{A}$	-	0.8	1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$I_F=10\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$	-	7	-	ns
Q_{rr}	Body Diode Reverse Recovery		-	5.9	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : $T_J=25^\circ\text{C}$, $V_{DD}=15\text{V}$, $V_{GS}=10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$, $I_{AS}=9\text{A}$

$T_J=25^\circ\text{C}$, $V_{DD}=-15\text{V}$, $V_{GS}=-10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$, $I_{AS}=-10\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

**P-Channel Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D = -250\mu\text{A}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -30\text{V}$, $V_{GS}=0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D = -250\mu\text{A}$	-1.0	-1.5	-2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS} = -10\text{V}$, $I_D = -10\text{A}$	-	21	27	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}$, $I_D = -5\text{A}$	-	31	43	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -15\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	1200	-	pF
C_{oss}	Output Capacitance		-	155	-	pF
C_{rss}	Reverse Transfer Capacitance		-	139	-	pF
Q_g	Total Gate Charge	$V_{DS} = -15\text{V}$, $I_D = -8\text{A}$, $V_{GS} = -10\text{V}$	-	52	-	nC
Q_{gs}	Gate-Source Charge		-	9.8	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	8.3	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -15\text{V}$, $I_D = -1\text{A}$, $V_{GS} = -10\text{V}$, $R_{\text{GEN}} = 6\Omega$ $R_D = 15\Omega$	-	13	-	ns
t_r	Turn-on Rise Time		-	15	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	198	-	ns
t_f	Turn-off Fall Time		-	98	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	-11	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-44	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s = -11\text{A}$	-	-0.8	-1.2	V
trr	Reverse Recovery Time	$T_J=25^\circ\text{C}$, $I_F=-2\text{A}$, $dI/dt=-100\text{A}/\mu\text{s}$	-	37	-	ns
Qrr	Reverse Recovery Charge		-	36	-	nC

Typical Performance Characteristics-N

Figure 1: Output Characteristics

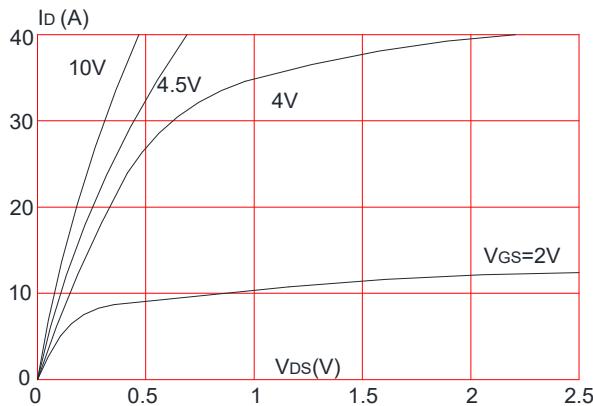


Figure 3: On-resistance vs. Drain Current

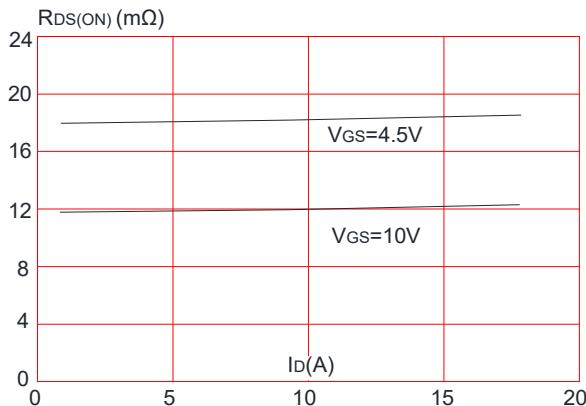


Figure 5: Gate Charge Characteristics

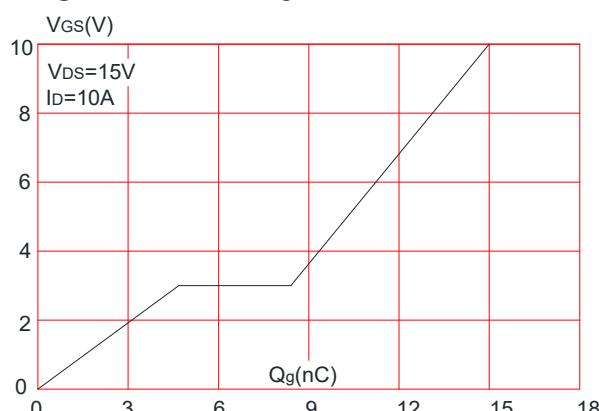


Figure 2: Typical Transfer Characteristics

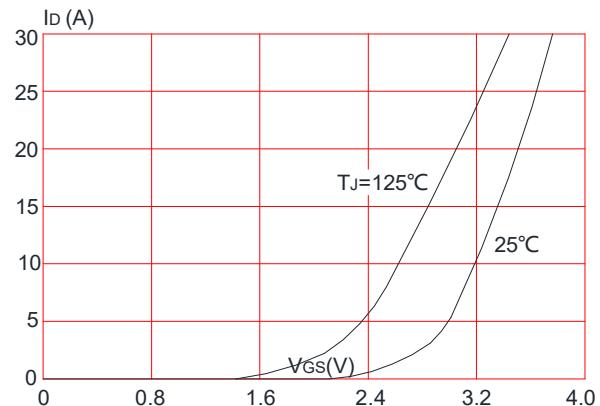


Figure 4: Body Diode Characteristics

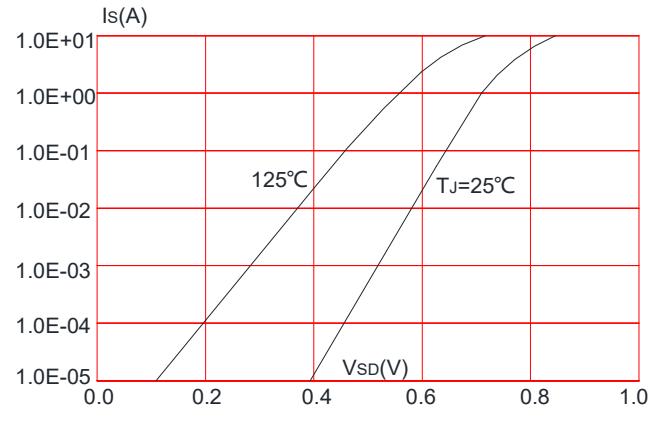


Figure 6: Capacitance Characteristics

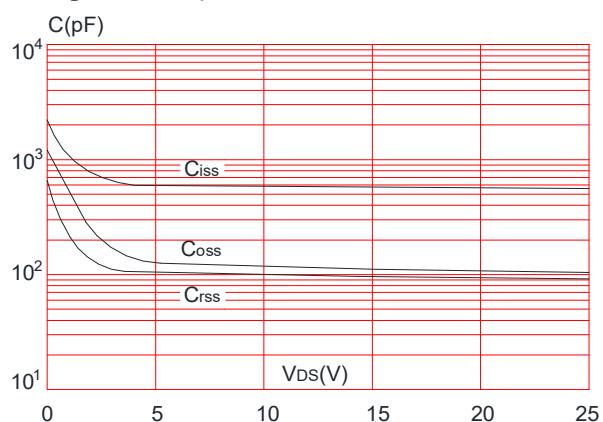


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

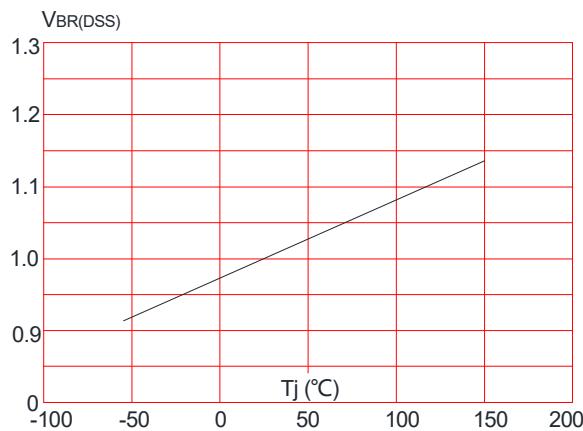


Figure 8: Normalized on Resistance vs. Junction Temperature

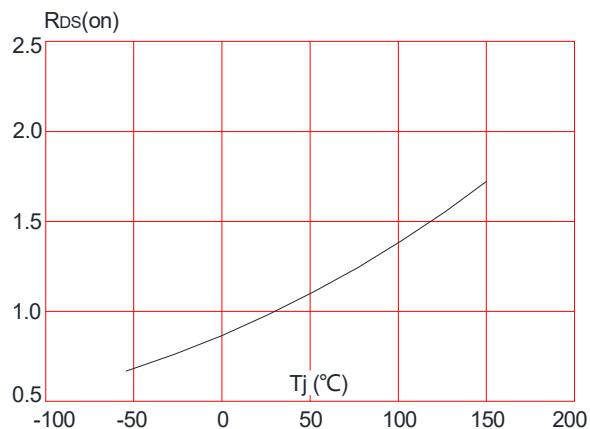


Figure 9: Maximum Safe Operating Area

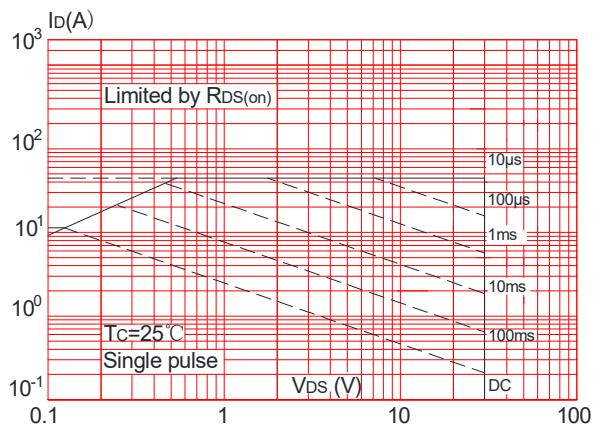


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

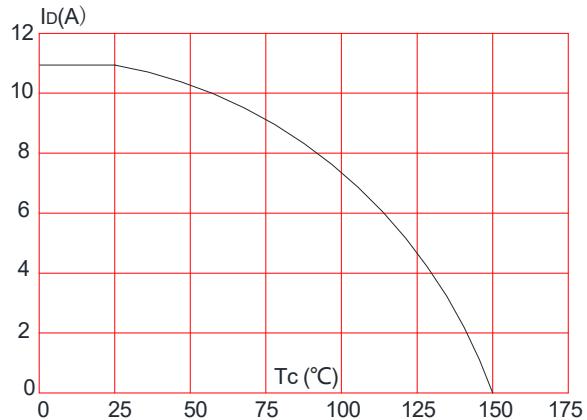
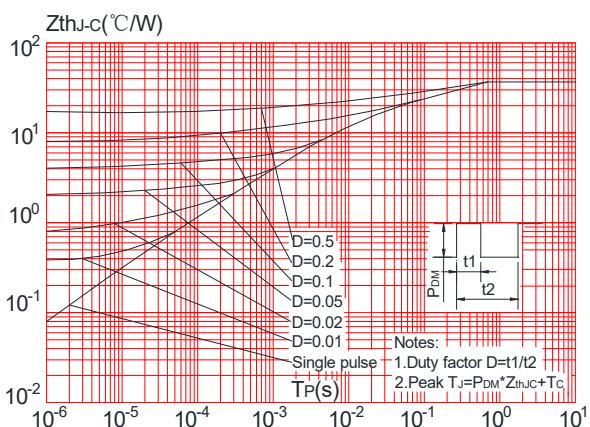


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



Test Circuit-N

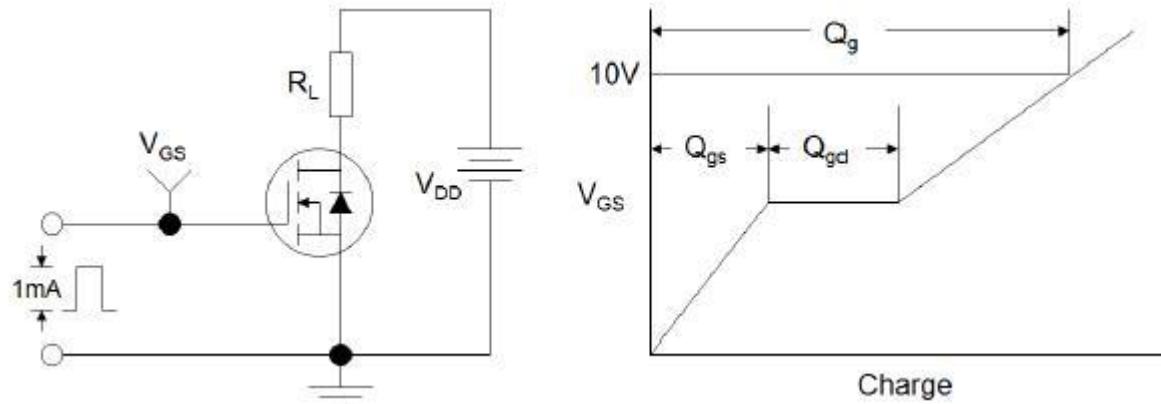


Figure1:Gate Charge Test Circuit & Waveform

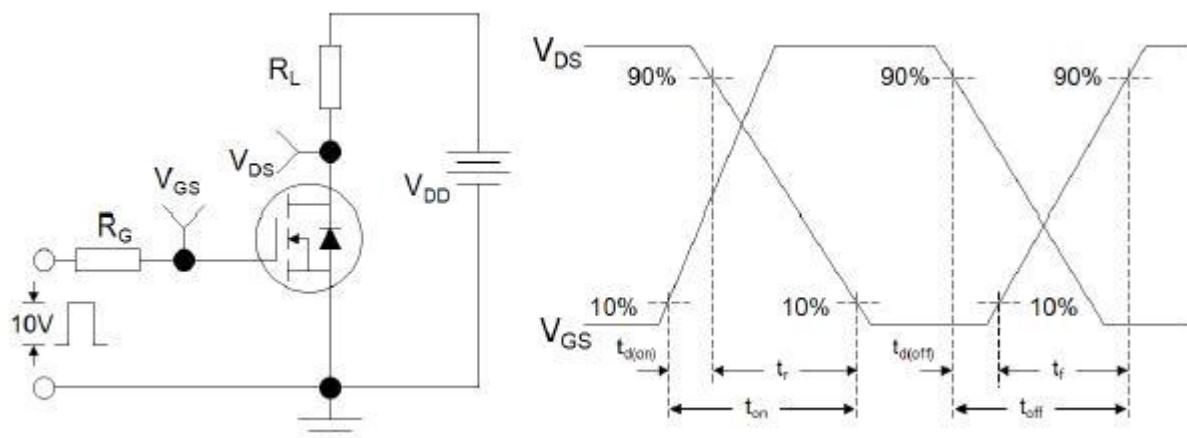


Figure 2: Resistive Switching Test Circuit & Waveforms

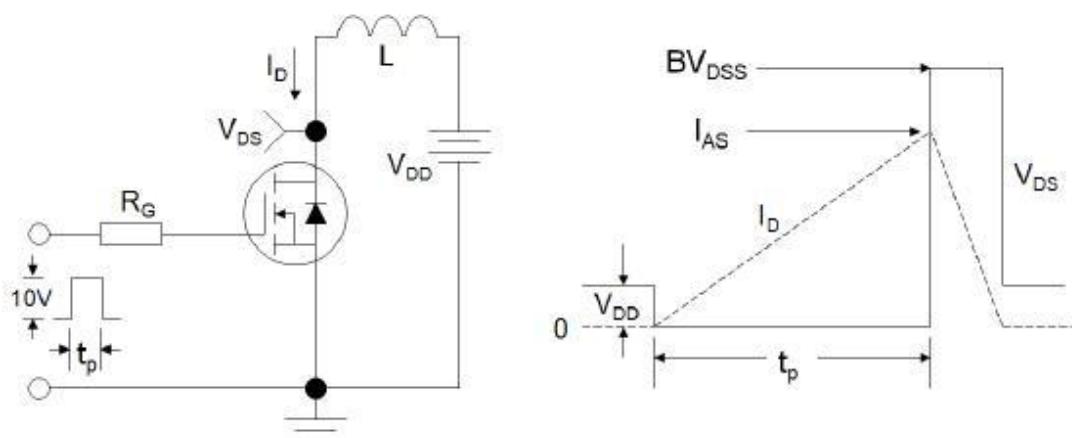


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

Typical Performance Characteristics-P

Figure 1: Output Characteristics

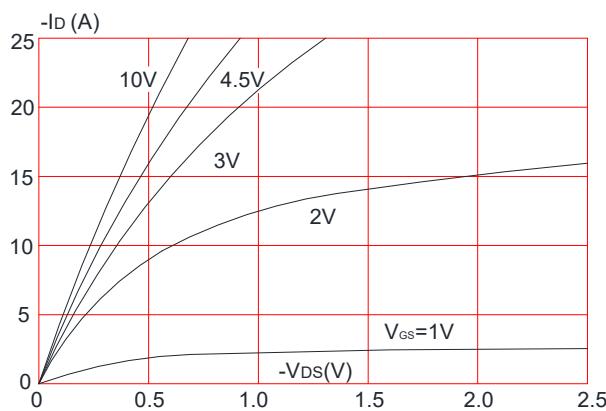


Figure 3: On-resistance vs. Drain Current

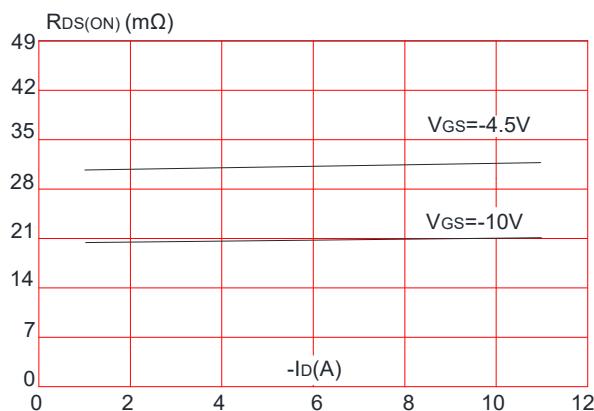


Figure 5: Gate Charge Characteristics

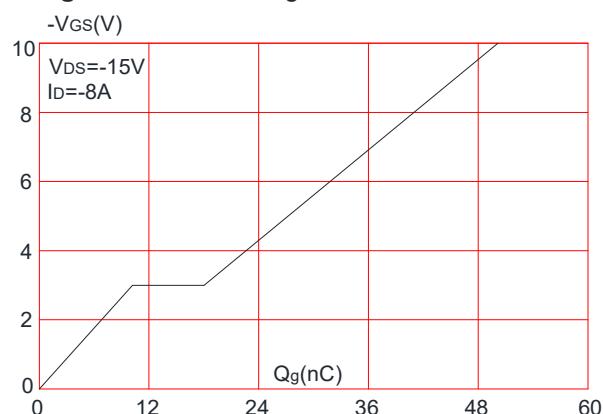


Figure 2: Typical Transfer Characteristics

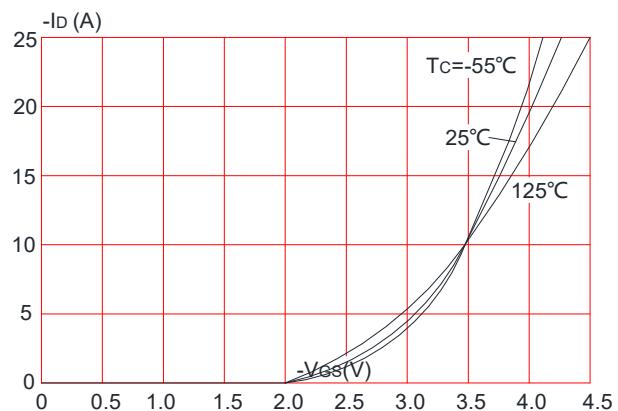


Figure 4: Body Diode Characteristics

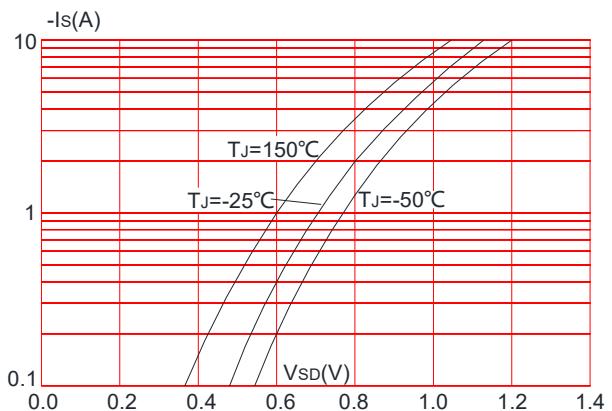


Figure 6: Capacitance Characteristics

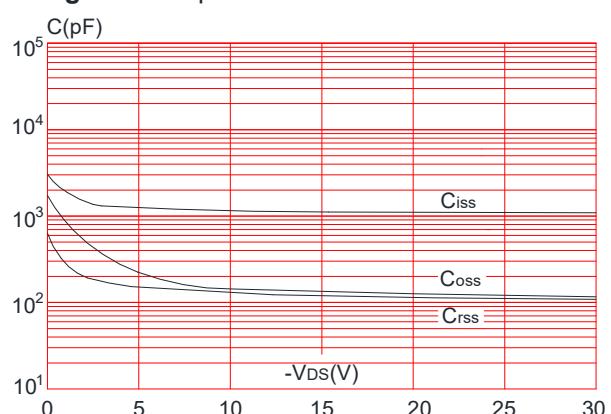


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

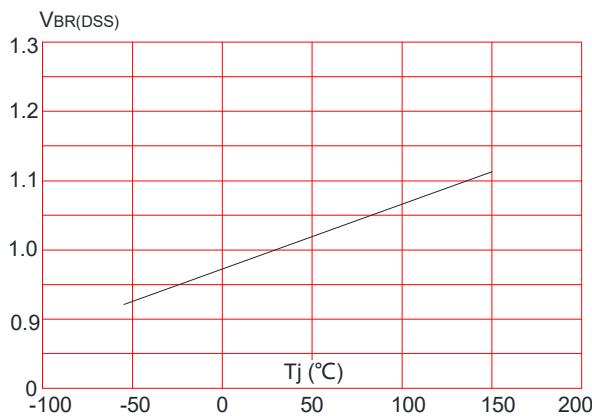


Figure 8: Normalized on Resistance vs. Junction Temperature

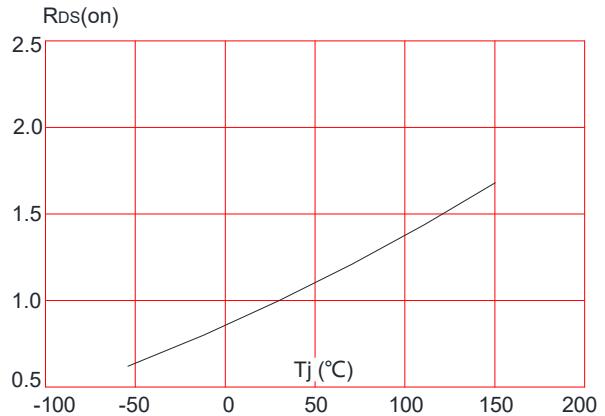


Figure 9: Maximum Safe Operating Area

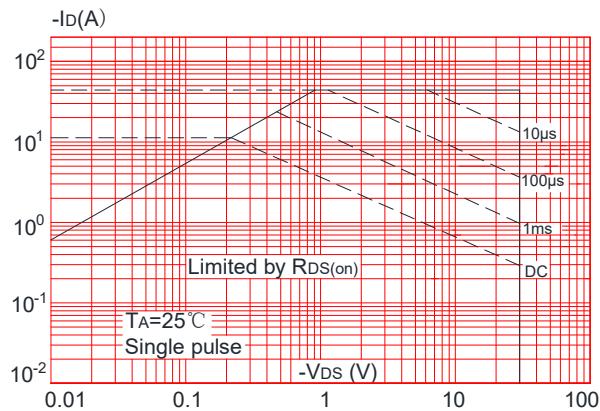


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

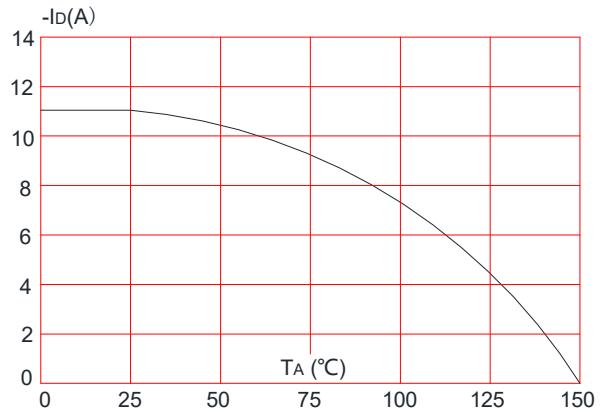
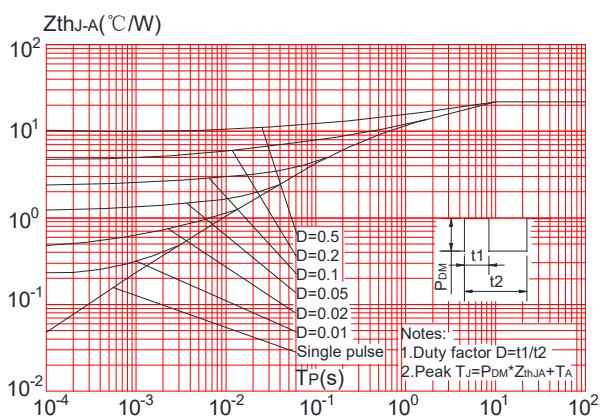
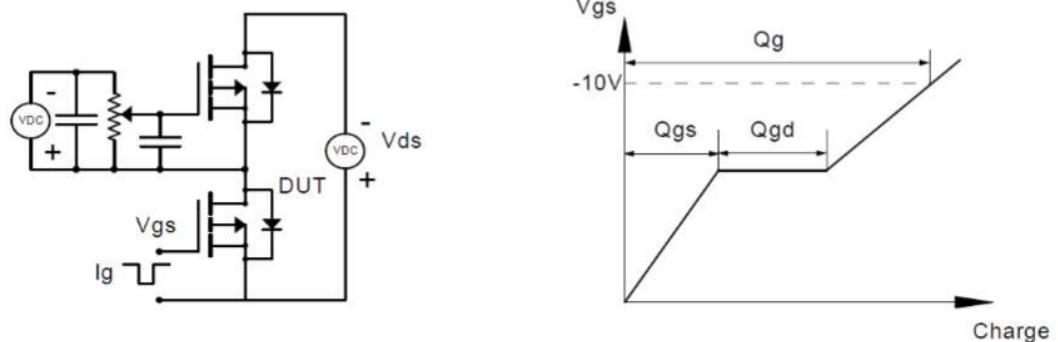


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

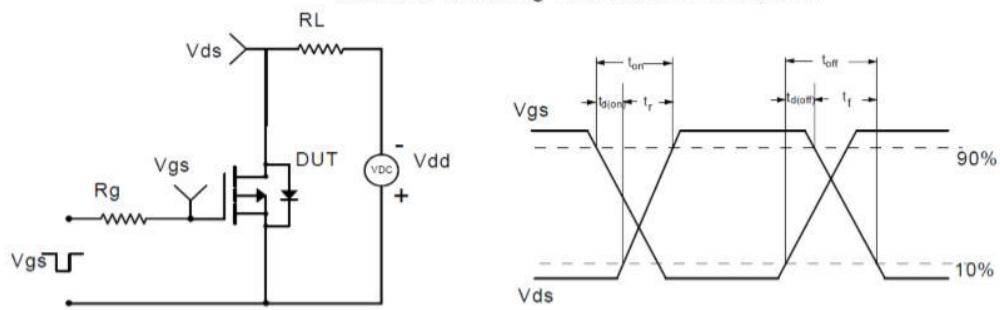


Test Circuit-P

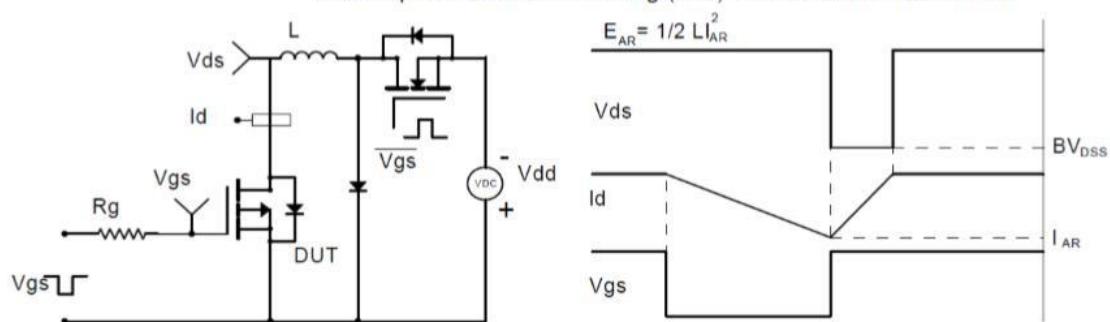
Gate Charge Test Circuit & Waveform



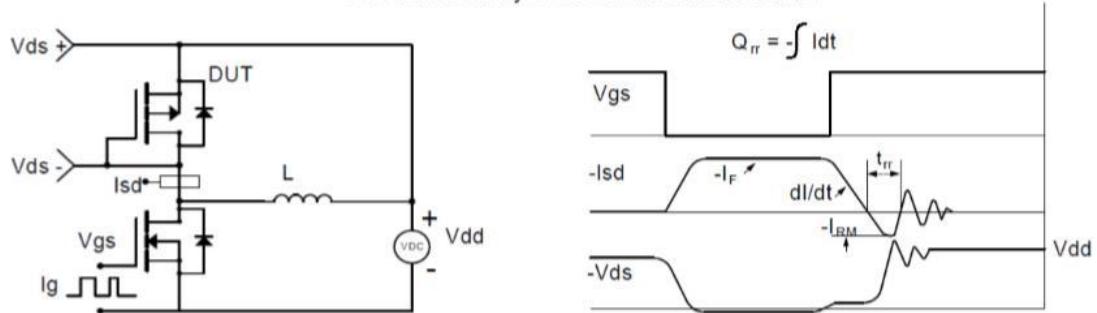
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

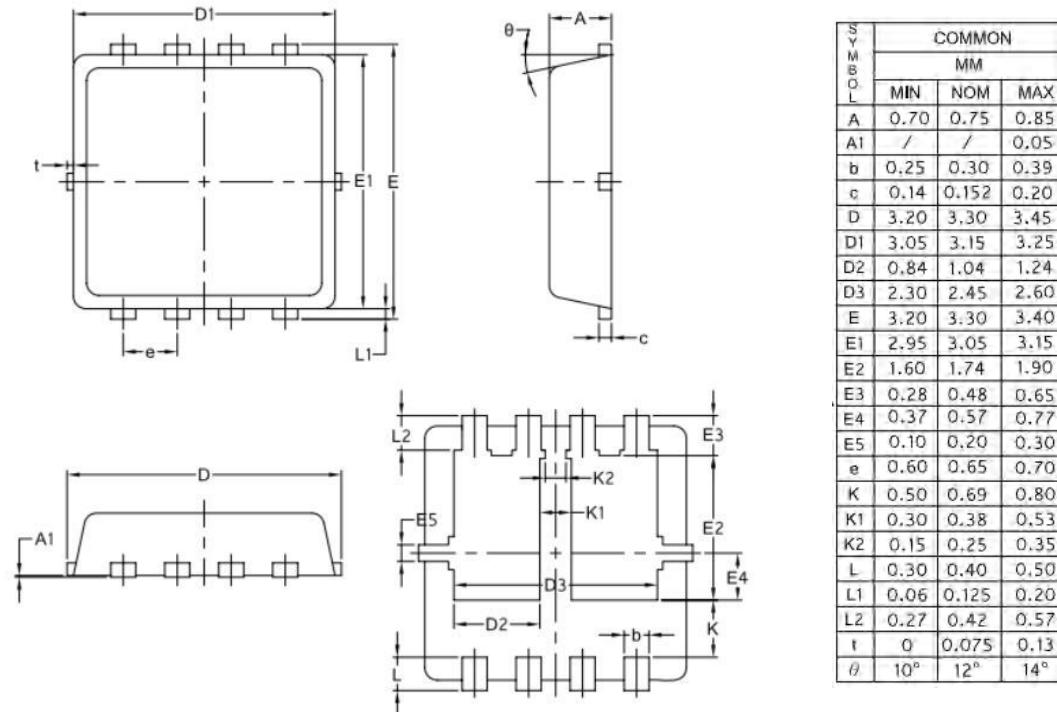


Diode Recovery Test Circuit & Waveforms

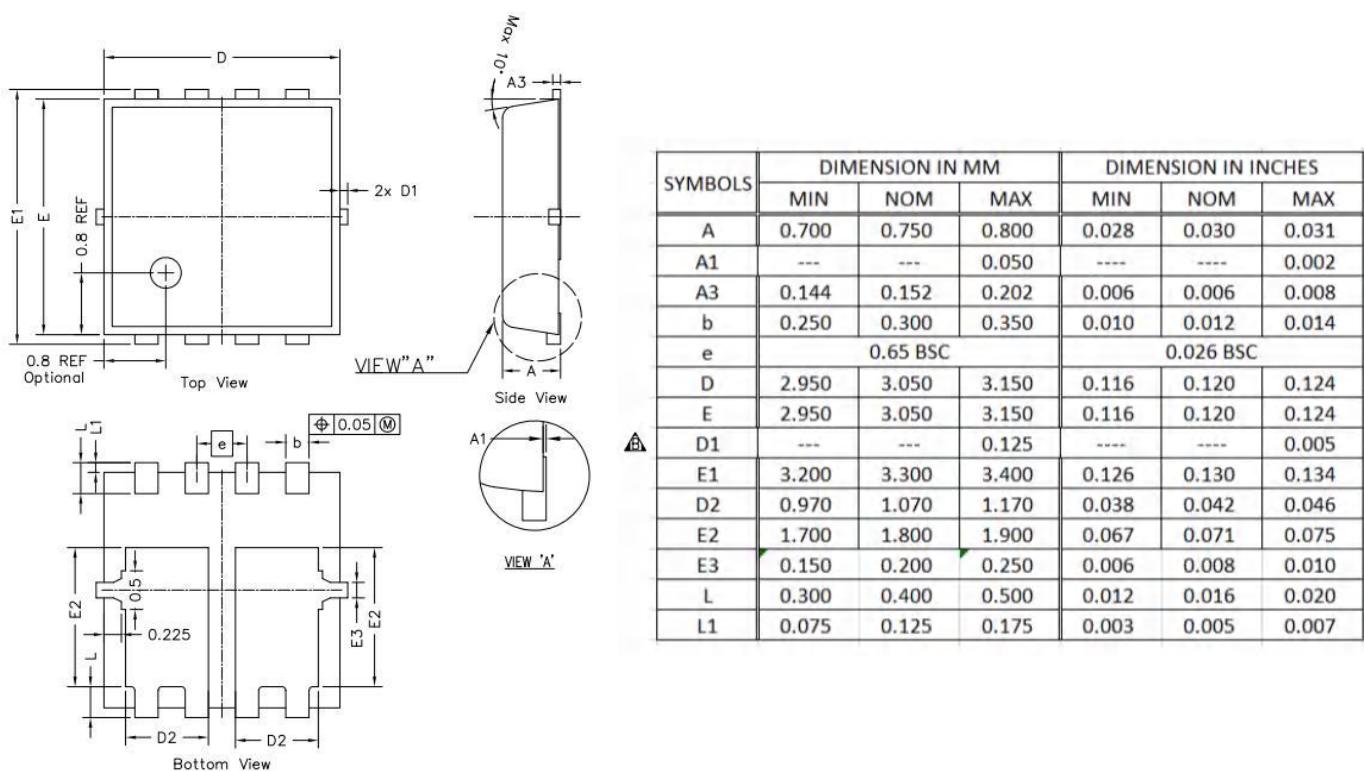




Package Mechanical Data-PDFN3x3-8L-D-Type A



Package Mechanical Data-PDFN3x3-8L-D-Type B





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